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BGA/CSP DEVELOPMENT UPDATE SERVICE

Fourth Quarter, 2003

The fourth quarter BGA/CSP update for 2003 features the market forecast in units for BGAs and CSPs by package construction. BGA categories include plastic, tape, and ceramic. CSP categories include rigid substrate, tape substrate, lead frame, and stacked die packages. The wafer level package forecast is provided in 200mm equivalents. Growth in the market is analyzed in light of the economic recovery with projections through 2008. An analysis of advanced packaging trends for BGAs and CSPs, including new developments in stacked die CSPs, is provided. Details of two new phones introduced by NEC are included—one with the first 0.4mm pitch part, the other a credit card size phone designed for the China market. A special section is devoted to laminate substrate capacity for CSPs, wire bond PBGAs, and flip chip substrates. New developments such as underfill jetting and Sharp's reliability data on the new plastic core solder balls are provided.

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Contents and specifications subject to change without notice. 4/8/04

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